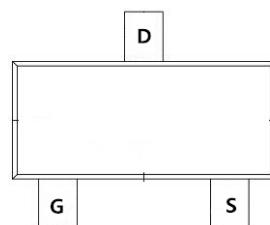
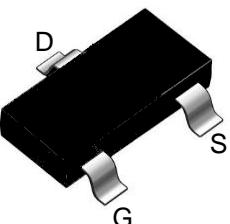
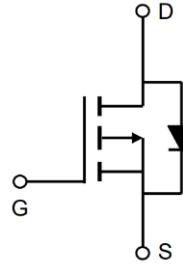


TM02P10I
P-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = -100V$ $I_D = -2.0A$</p> <p>$R_{DS(ON)} = 290m\Omega$ (Typ.) @ $V_{GS} = -10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 																										
I:SOT-23																											
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TM02P10I
P-Channel Enhancement Mosfet

Electrical Characteristics: ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	-100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-80\text{V}$	---	---	-1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	-1	-1.9	-4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-4\text{A}$	---	290	300	$\text{m}\Omega$
G_{FS}	Forward Transconductance	$V_{\text{DS}}=-4.5\text{V}, I_{\text{D}}=-1\text{A}$	---	1	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	590	---	pF
C_{oss}	Output Capacitance		---	170	---	
C_{rss}	Reverse Transfer Capacitance		---	45	---	
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-25\text{V}, RL=6\Omega, ID=-2\text{A}$ $V_{\text{GEN}}=-10\text{V}, RG=6\Omega$	---	9.6	---	ns
t_r	Rise Time		---	29	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	21	---	ns
t_f	Fall Time		---	25	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-25\text{V}, I_{\text{D}}=-2\text{A}$	---	6	18	nC
Q_{gs}	Gate-Source Charge		---	1.15	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	3	---	nC
Drain-Source Diode Characteristics						
TRR	Source-Drain Reverse Recovery Ti	---	10	20	NS	
I_s	Diode Forward Current	---	---	---	-1.25	A
LSM	Pulsed Current	---	--	---	-10	A

Note :

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t < 5$ sec.
3. Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing

Typical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

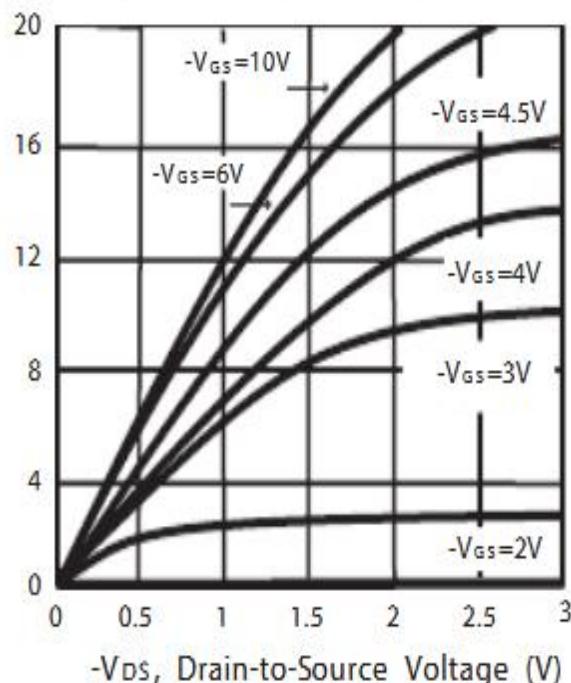


Figure 1. Output Characteristics

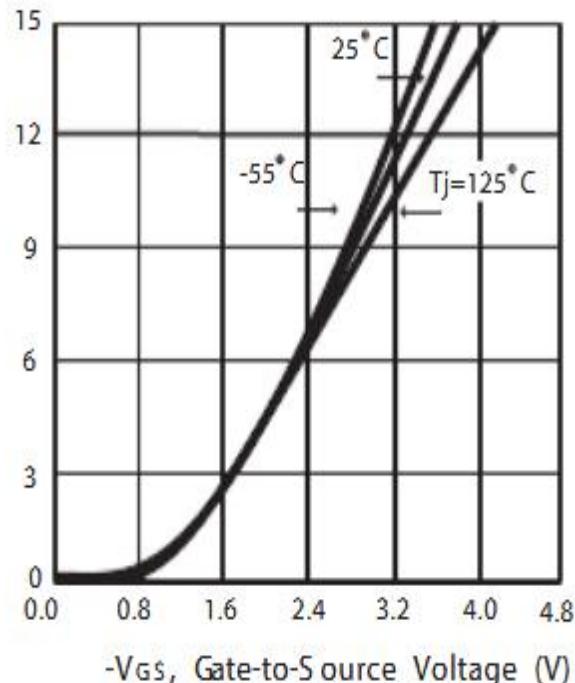


Figure 2. Transfer Characteristics

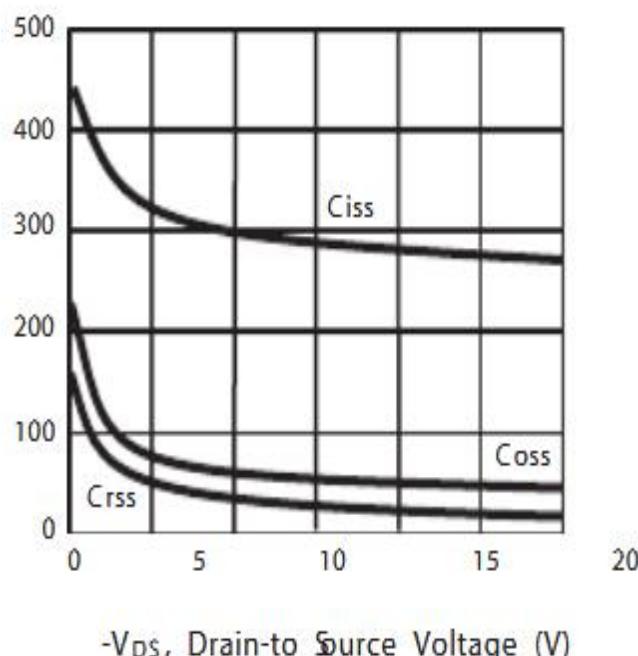


Figure 3. Capacitance

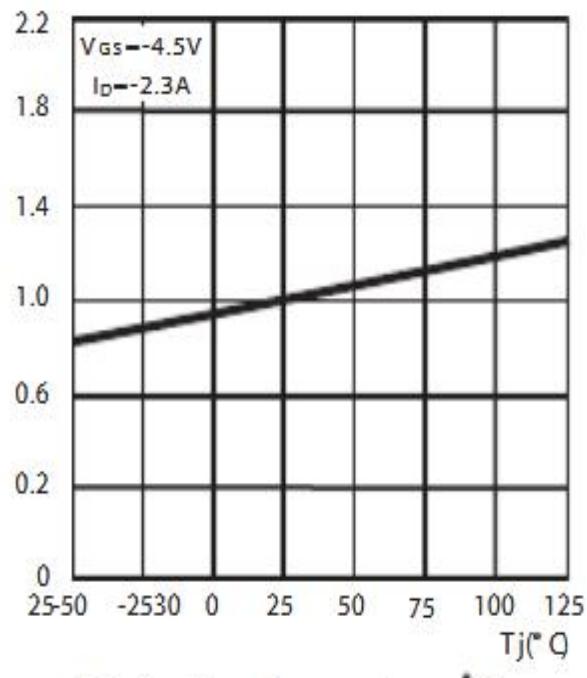
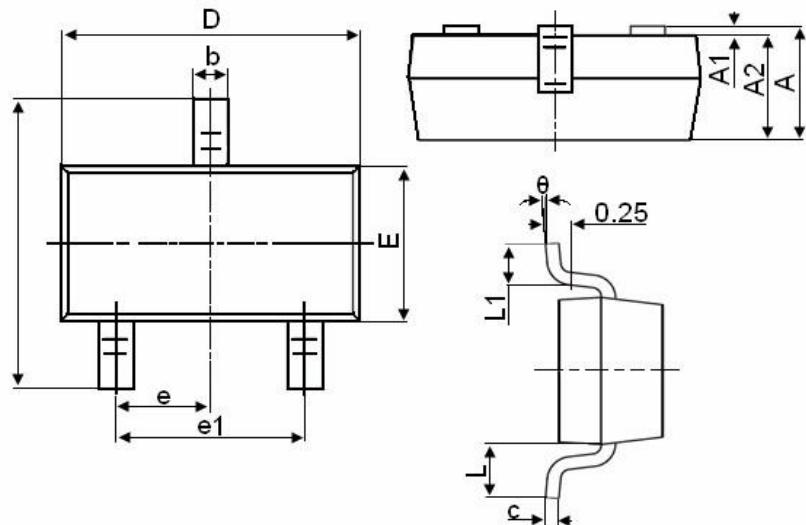


Figure 4. On-Resistance Variation with Temperature

Package Mechanical Data:SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°